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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Confirmation No.: 2221

Myounggoo LEE et al.

Art Unit: 1753

Application No.: 10/658,460

Examiner: Rodney Glenn McDONALD

Filed: September 10, 2003

Attorney Docket No.: 029567-00004

For: BIAS SPUTTERING FILM FORMING PROCESS AND BIAS SPUTTERING FILM FORMING APPARATUS

REQUEST FOR RECONSIDERATION

MAIL STOP AMENDMENT

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

November 13, 2007

Sir:

The Office Action dated August 20, 2007, has been received and carefully noted. The following remarks are being submitted as a full and complete response thereto. Reconsideration of the rejections of the claims is respectfully requested in light of the following remarks. Claims 1-6 are pending in this application.

The Office Action rejects claims 5-6 under 35 U.S.C. § 102(b) as being anticipated by Miyoshi et al. (JP 07-018431); claims 1, 3 and 4 under 35 U.S.C. § 103(a) over Iacoponi et al. (U.S. Patent No. 6,261,946) in view of Ikeda (JP 63-278252) and Miyoshi; and claim 2 under 35 U.S.C. § 103(a) as being obvious over Iacoponi in view of Ikeda and Miyoshi and further in view of Mamoru (JP 2000-096223). The rejections are respectfully traversed.

In particular, the above-identified application claims a bias sputtering film forming apparatus that includes a power source of variable output against a substrate electrode